



Material Content Data Sheet



Sales Product Name		TLE42994E V33		Issued		24. January 2018		
MA#		MA001790340						
Package		PG-SSOP-14-2		Weight*		83.48 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.995	3.59	3.59	35880	35880
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		103	
	non noble metal	zinc	7440-66-6	0.034	0.04		413	
	non noble metal	iron	7439-89-6	0.689	0.83		8254	
wire	non noble metal	copper	7440-50-8	27.978	33.51	34.39	335129	343899
	noble metal	gold	7440-57-5	0.153	0.18	0.18	1830	1830
	encapsulation	organic material	carbon black	1333-86-4	0.097	0.12		1159
plastics	plastics	epoxy resin	-	4.451	5.33		53312	
	inorganic material	silicondioxide	60676-86-0	43.830	52.50	57.95	525010	579481
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11692	11692
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9195	9195
glue	plastics	epoxy resin	-	0.376	0.45		4506	
	noble metal	silver	7440-22-4	1.128	1.35	1.80	13517	18023
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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